

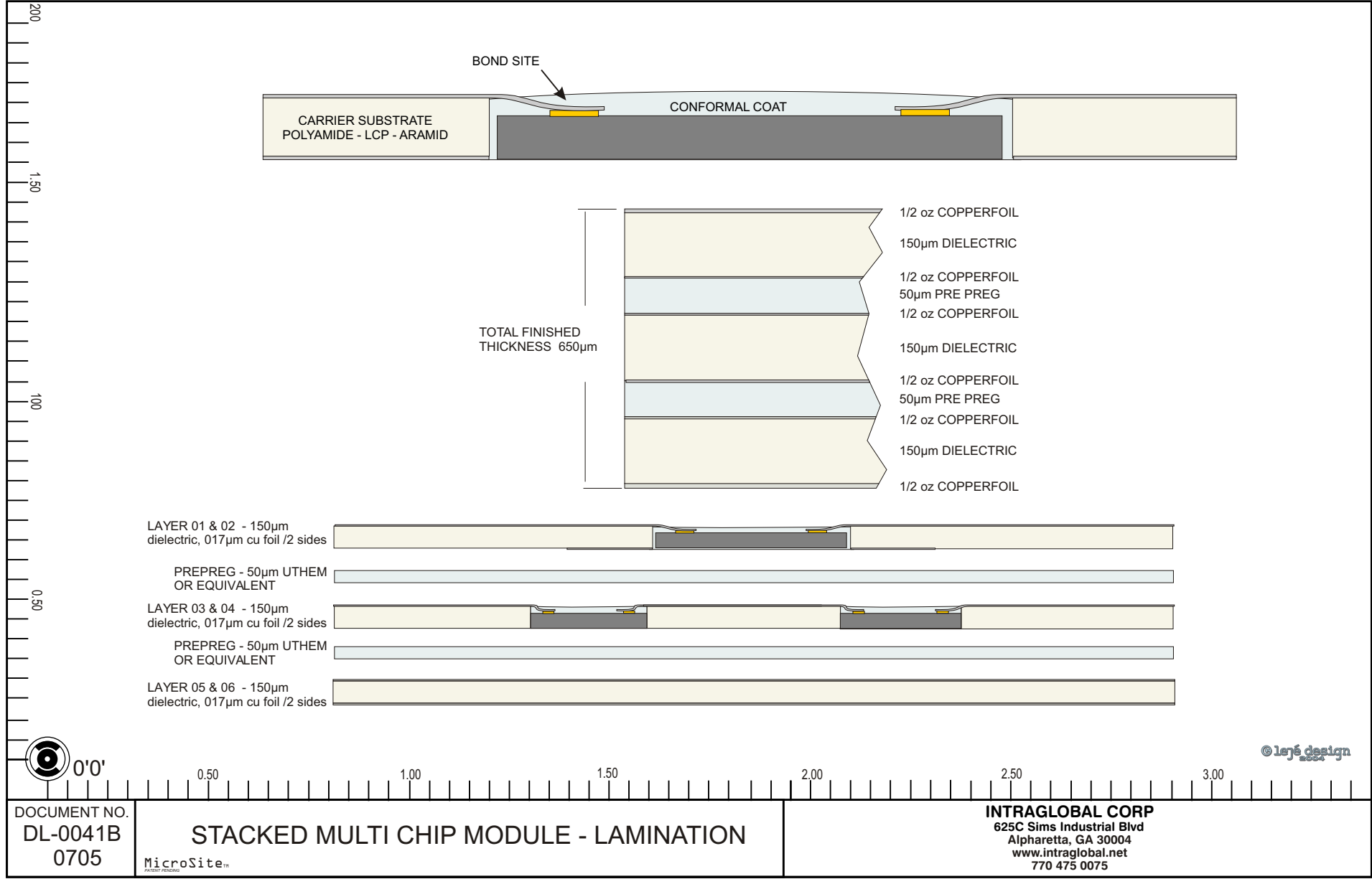
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DOCUMENT NO.
DL-0041A
0705

MicroSite[™]
PATENT PENDING

STACKED MULTI CHIP MODULE - LAYER

INTRAGLOBAL CORP
625C Sims Industrial Blvd
Alpharetta, GA 30004
www.intraglobal.net
770 475 0075



BOND SITE

CARRIER SUBSTRATE
POLYAMIDE - LCP - ARAMID

CONFORMAL COAT

TOTAL FINISHED
THICKNESS 650µm

1/2 oz COPPERFOIL
150µm DIELECTRIC
1/2 oz COPPERFOIL
50µm PRE PREG
1/2 oz COPPERFOIL
150µm DIELECTRIC
1/2 oz COPPERFOIL
50µm PRE PREG
1/2 oz COPPERFOIL
150µm DIELECTRIC
1/2 oz COPPERFOIL

LAYER 01 & 02 - 150µm
dielectric, 0.17µm cu foil /2 sides

PREPREG - 50µm UTHEM
OR EQUIVALENT

LAYER 03 & 04 - 150µm
dielectric, 0.17µm cu foil /2 sides

PREPREG - 50µm UTHEM
OR EQUIVALENT

LAYER 05 & 06 - 150µm
dielectric, 0.17µm cu foil /2 sides

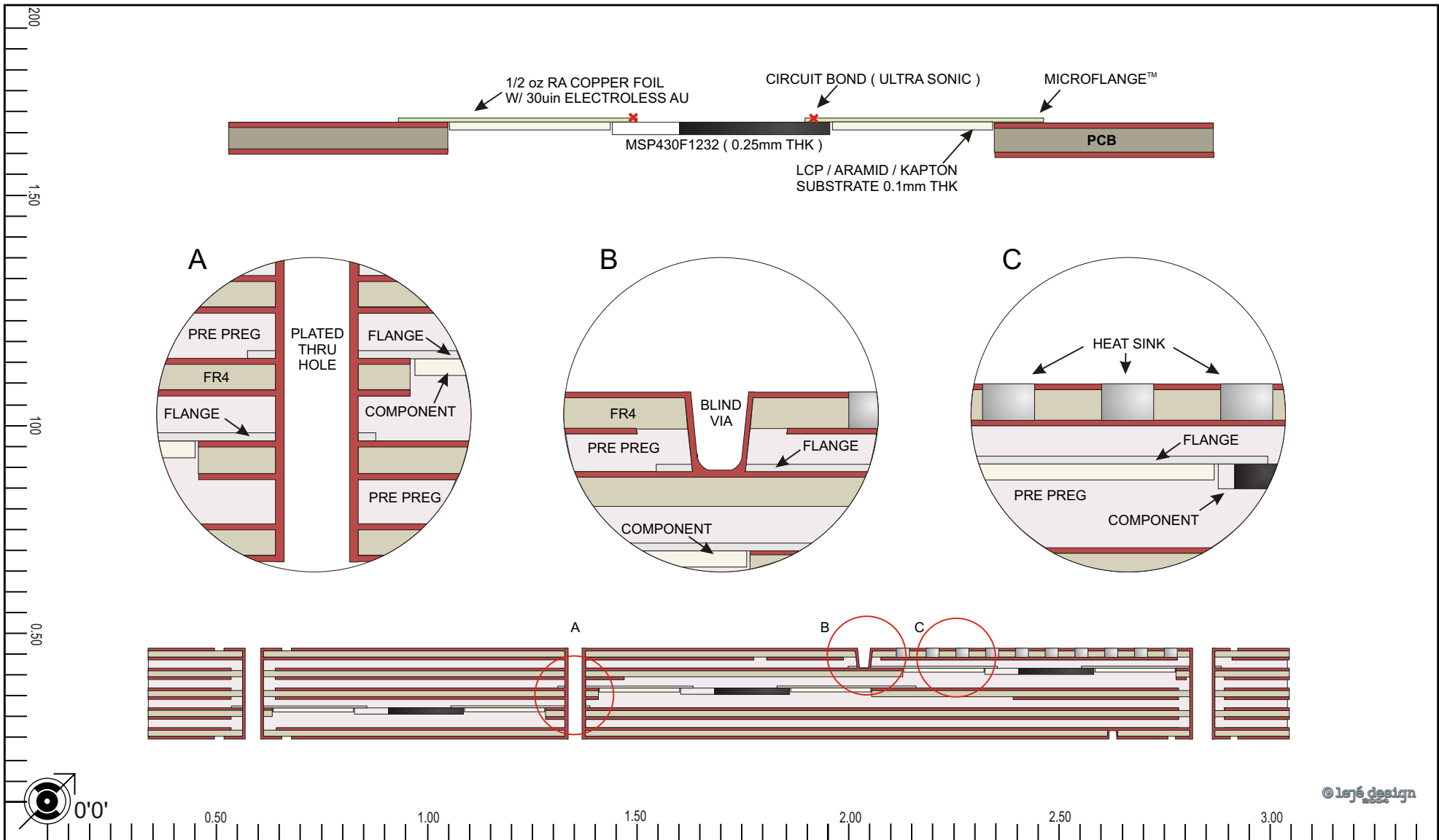
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STACKED MULTI CHIP MODULE - LAMINATION

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